

**MS Exam, Fall 2012, Solid State Electronic Devices (ECE 230A-B)**

**ECE230A:**

1. III-V compound semiconductor GaAs has two families of cleavage planes (110) and (1 $\bar{1}$ 0). You can cut the crystal along these two planes to create mirror-like facets. This is how semiconductor lasers are fabricated (i.e. using the cleaved planes as reflecting mirrors). For a (211) GaAs wafer, find
  - a. the cleavage plane(s) that can cut through the (211) wafer with a mirror-like facet,
  - b. the plane that is normal to both the (211) plane and the cleavage plane(s) in (a),
  - c. what is the lattice structure of GaAs and InP?
  - d. The lattice constant for GaAs is 5.65 Å. Find the interplane distances for (111) planes and (211) planes,
  - e. Calculate the bond length of GaAs crystal.

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**ECE 230B:**

Assume silicon, room temperature, complete ionization.

1. For an abrupt n<sup>+</sup>-p diode in Si, the n<sup>+</sup> doping is 10<sup>20</sup> cm<sup>-3</sup>, the p-type doping is 3×10<sup>16</sup> cm<sup>-3</sup>. Assume room temperature and complete ionization.
  - (a) Draw the band diagram at zero bias. Indicate  $x = 0$  as the boundary where the doping changes from n<sup>+</sup> to p. Also indicate where the Fermi level is with respect to the midgap.
  - (b) Write the equation and calculate the built-in potential.
  - (c) Write the equation and calculate the depletion width.
  - (d) Will the built-in potential increase or decrease if the temperature goes up and why?
  
2. Consider an n-channel MOSFET with 20 nm thick gate oxide and uniform p-type substrate doping of 10<sup>17</sup> cm<sup>-3</sup>. The gate work function is that of n<sup>+</sup> Si.
  - (a) What is the threshold voltage? Sketch the band diagram at threshold condition,  $\psi_s = 2\psi_B$ .
  - (b) What is the threshold voltage if a reverse bias of 1 V is applied to the substrate? Sketch the band diagram at threshold.